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Title: Detonator Production Overview - Supply Chain Collaboration

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Intended for: Presentation to potential supply chain partners

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Detonator Production Overview

Supply Chain Collaboration



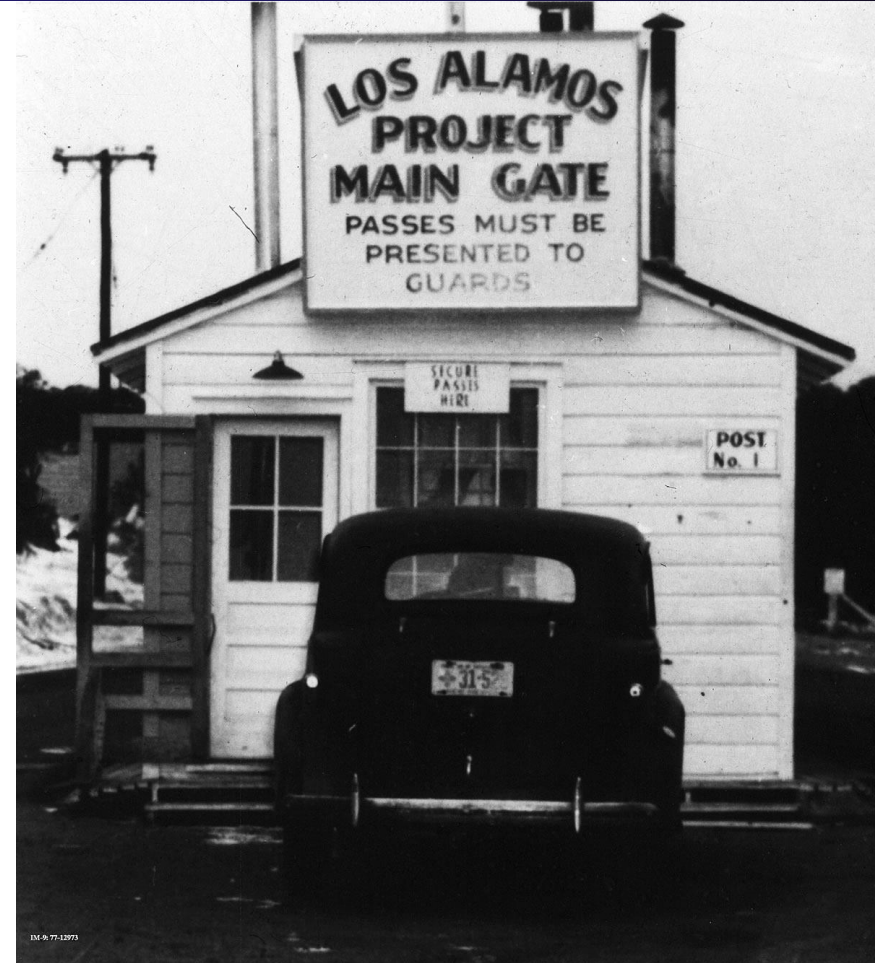
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Presentation Outline

- Los Alamos National Laboratory
 - History and WWII legacy
 - Today's Laboratory mission
- Detonator manufacturing in the Nuclear Security Enterprise
 - Evolution of detonator mission at LANL
 - Detonator Production today
- Manufacturing processes
 - Design of a detonator
 - In-house production capabilities
- Expanding our supply chain

Origins of the Lab

- Founded in 1943 to lead the Manhattan Project during WWII
- U.S. government assumed ownership of Los Alamos Ranch School in a remote, mountainous region of northern New Mexico
- Responsible for the development of the first nuclear weapons systems (Little Boy and Fat Man)
- Formally established as a government research facility under the Department of Energy (DOE) after WWII



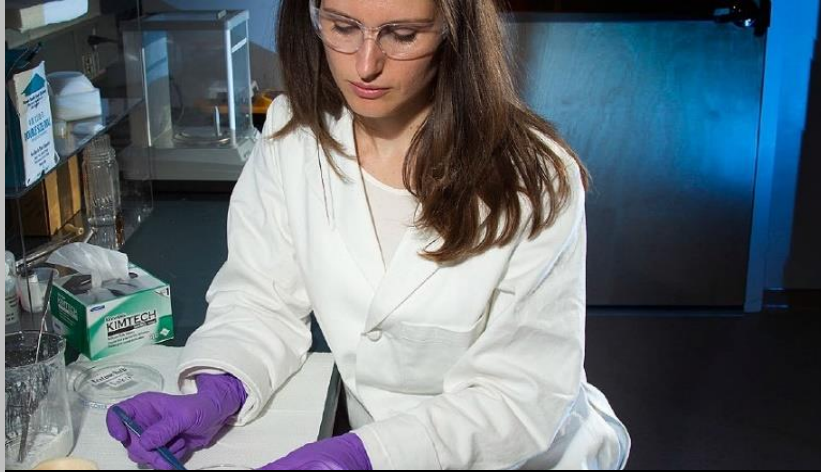
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Delivering the Best Science and Technology

- Mission
 - To solve national security challenges through scientific excellence
- Vision
 - To deliver science and technology to protect our nation and promote world stability
- Values
 - Service
 - Excellence
 - Integrity
 - Teamwork
 - Stewardship
 - Safety and Security



Key Focus Areas



- Nuclear deterrence
- Stockpile stewardship
- Nuclear threat protection
- Cybersecurity threat mitigation
- Energy security solutions
- High performance computing
- Space research
- Health and biosciences
- Earth and environment



Timeline of Detonator Production at LANL

- 1943** Wartime R&D begins
- 1949** Production begins at Picatinny Ars.
- 1950** Production ceases at LANL
- 1956** Production moves to Mound, OH
- 1993** Mound plant closes
- 1995** LANL receives production mission
- 1999** First stockpile product shipped
- 2007** First LANL-designed product ships
- 2018** Mission and R&D increases



Detonator Facility Evolution

“Trap Door” Site (Circa 1950)



R&D environment, minimal infrastructure

Technical Area 22 (Present Day)



10+ production lines, 120+ staff, \$42M budget

Essential to the Stockpile

Mission Assignments

- Production
 - W76, W78, W88 stockpile
 - W88 refresh
 - W80 and B61 LEP
 - W87 stockpile (future)
- Surveillance
 - All LANL systems
- Research & Development
 - New designs
 - Advanced concepts
 - Hydrotesting
 - Stockpile concerns
 - Global security

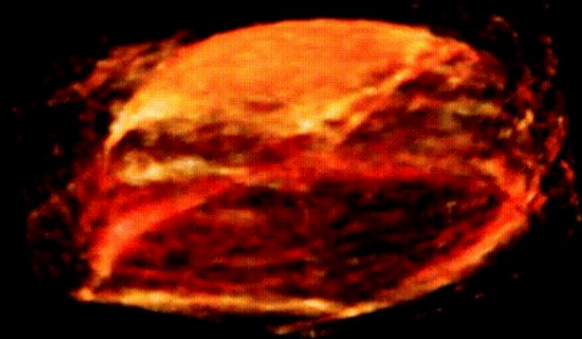
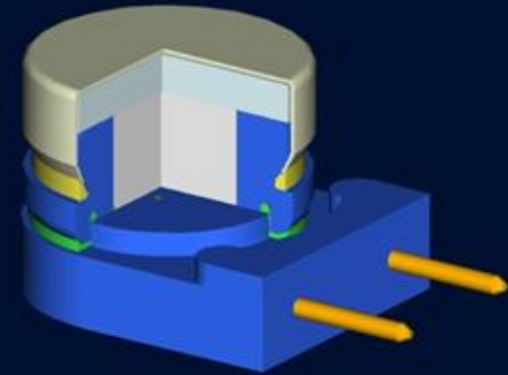


Mission Deliverables

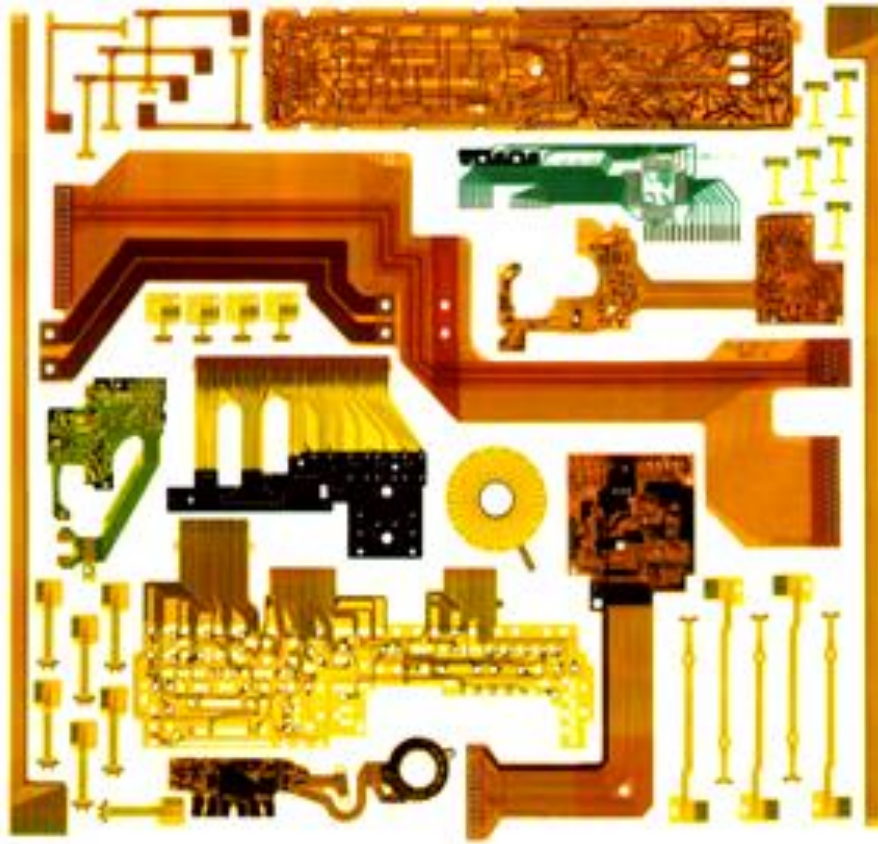
- Production
 - 1E33, 1E38, 1E40, 4E10
 - MC5108 detonator
 - Actuators
 - Cables
- Surveillance
 - Annual assessment reports
- Research & Development
 - Hydrotest cables
 - LEP development
 - Test hardware
 - Special projects

Detonator Components

- Bill of materials
 - Cup
 - High explosive (HE) powder
 - Header preload
 - Cable
- Typical production processes
 - High density pressing
 - Low density pressing
 - Cable manufacturing
 - Assembly
 - Non-destructive testing
 - Test fire (as required)



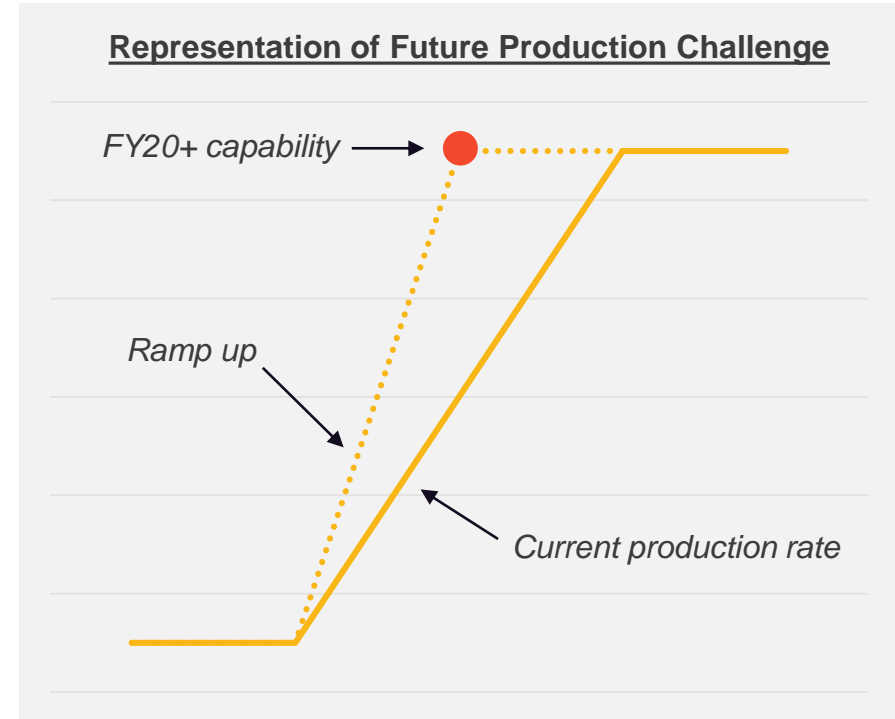
Production Capabilities



- High explosive (HE) components
- Inert components
- Processes
 - HE pressing
 - Laser welding
 - Photolithography
 - Polymer potting and molding
 - Glass ceramic sealing
 - Cable manufacturing
 - Manual component assembly
 - Electrical testing

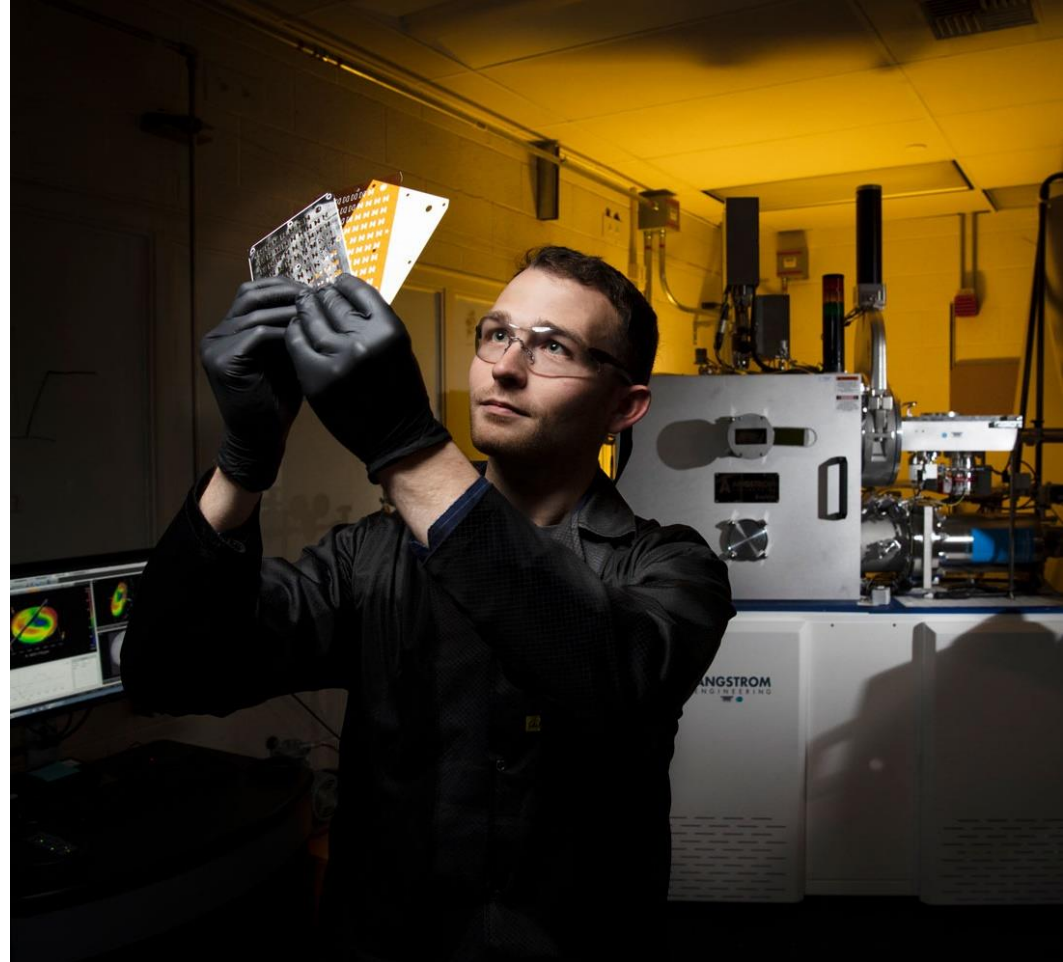
Increasing Production Scope

- Challenges to our division
 - Process development
 - Staffing
 - Production space
 - Facility upgrades
- Challenges to our suppliers
 - Vendor qualification burden
 - Low production quantities
 - Document handling and storage
 - Rigor of quality requirements
- ***We need your help!***



Supply Chain Partnership

- Product line components
 - Cables
 - Connectors
 - Cups
 - Electronic assemblies
- Future design concepts
 - Miniaturized capacitors
 - Switches
 - Voltage converters
 - Optical charging
 - Microelectronics

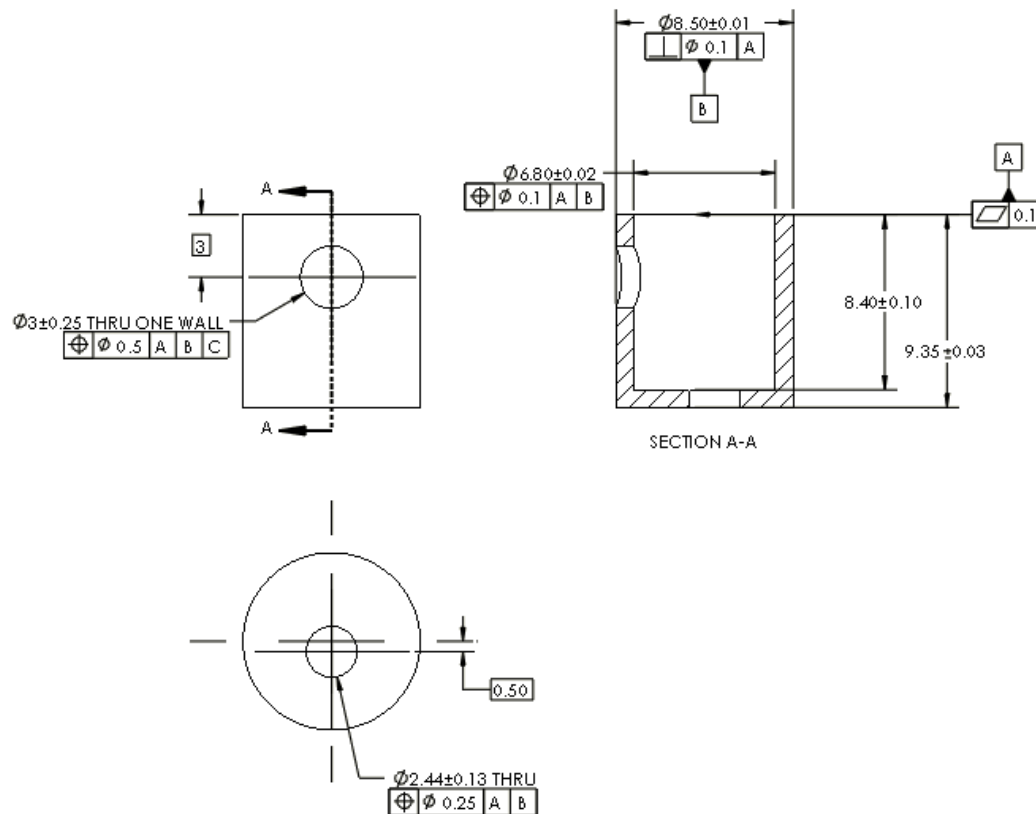


Manufacturing Needs

- Machining
 - 5-axis machining with non-chlorinated coolant
 - Centerless grinding (± 0.00025 " diametrical tolerance)
 - High-speed (50k+ rpm) multi-material plunge grinding
 - Ultrasonic machining
- Electronic
 - Potting and encapsulation
 - SMT assembly
 - Radiation-hardened components
- Value-added services
 - CMM and advanced inspection methods
 - Electroplating

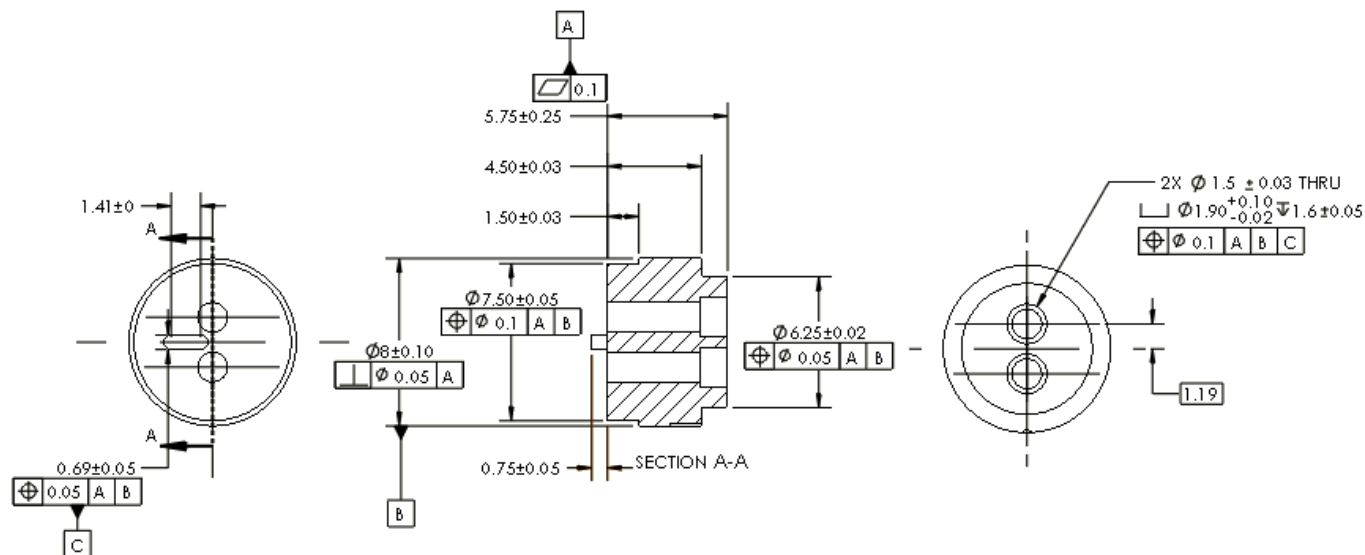
Sample Parts

Sleeve (PEEK)



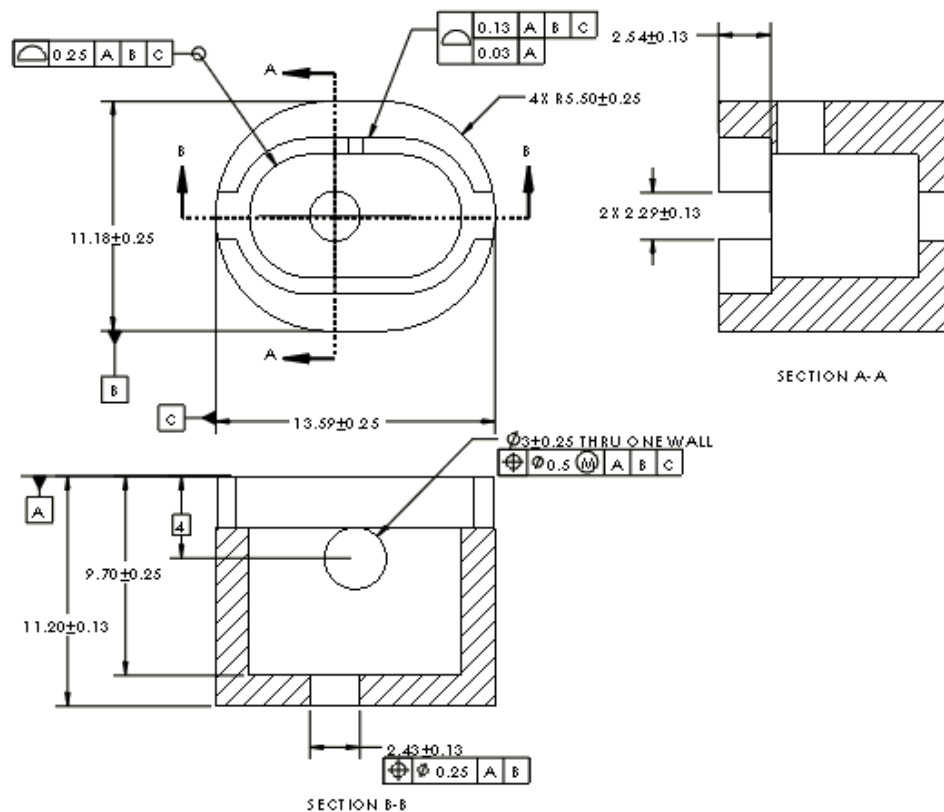
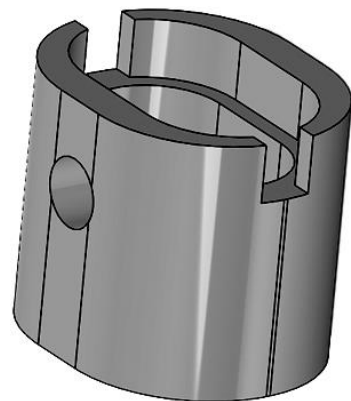
Process: CNC machining

Connector (PEEK)



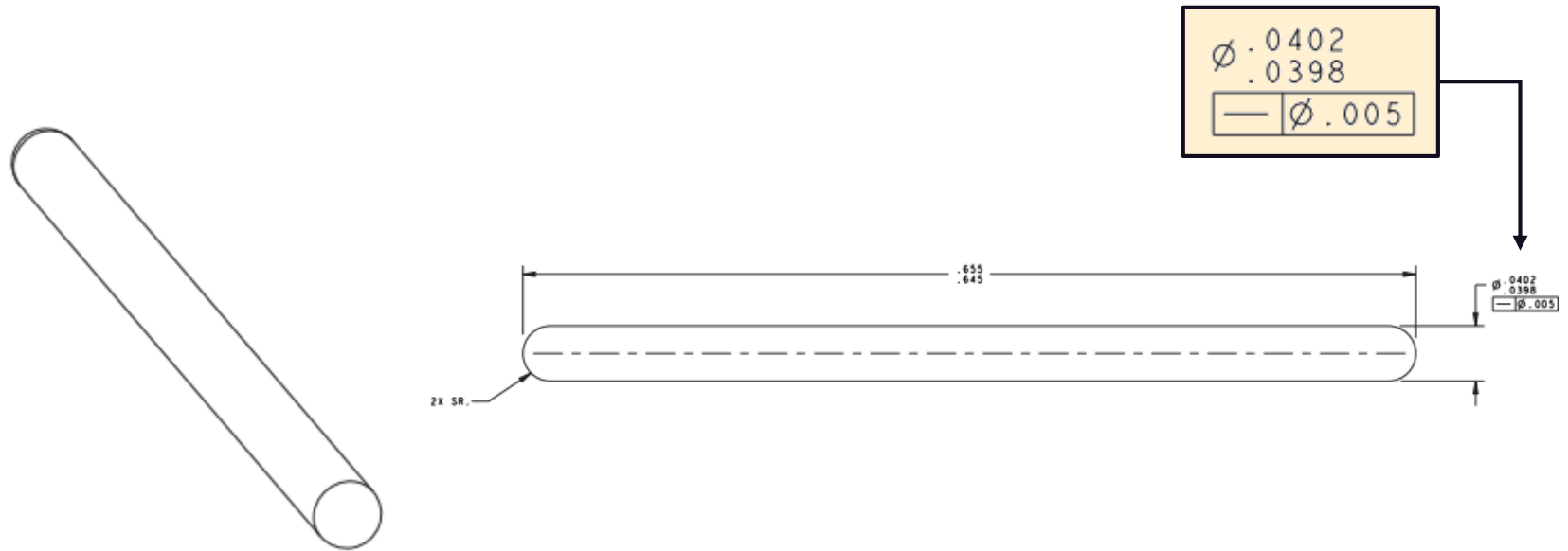
Process: CNC machining

Clip (PEEK)



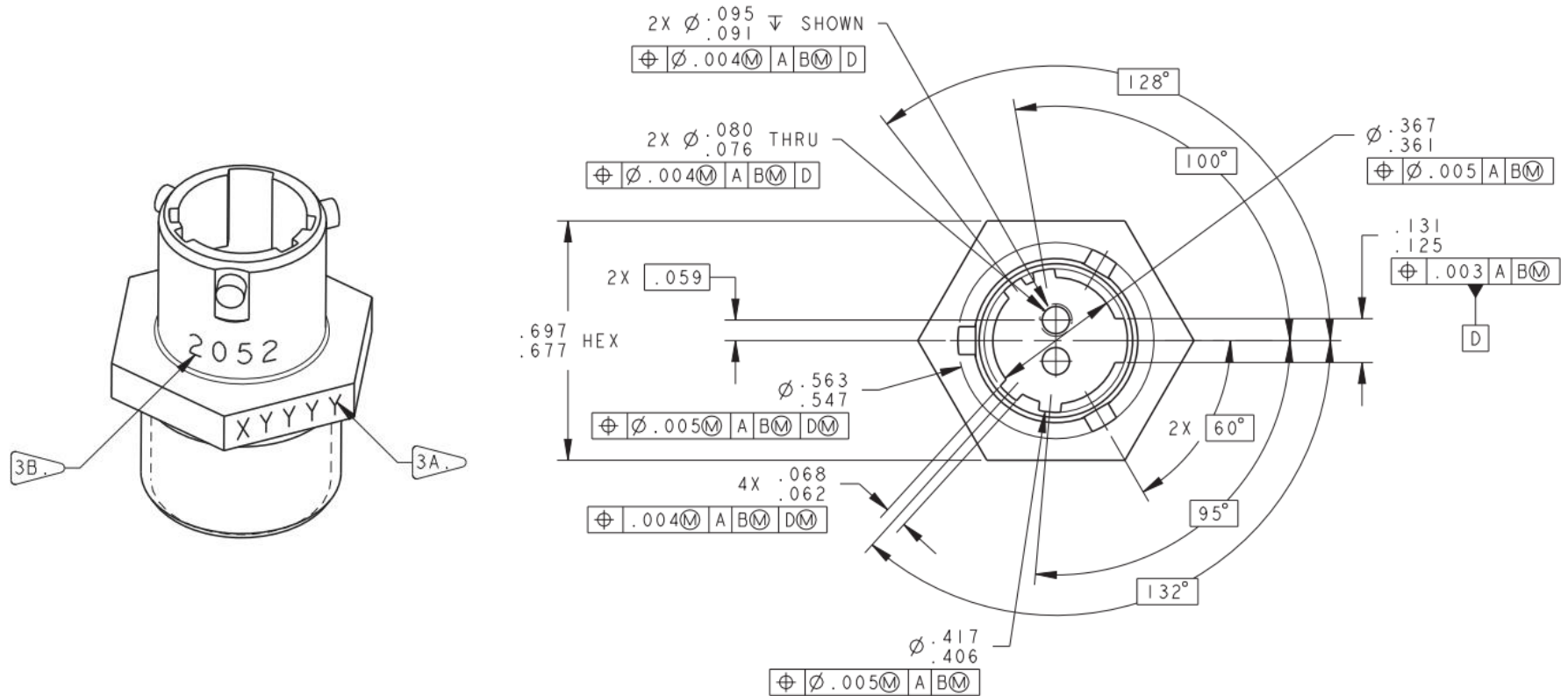
Process: CNC machining

Pin (Hastelloy C-276)



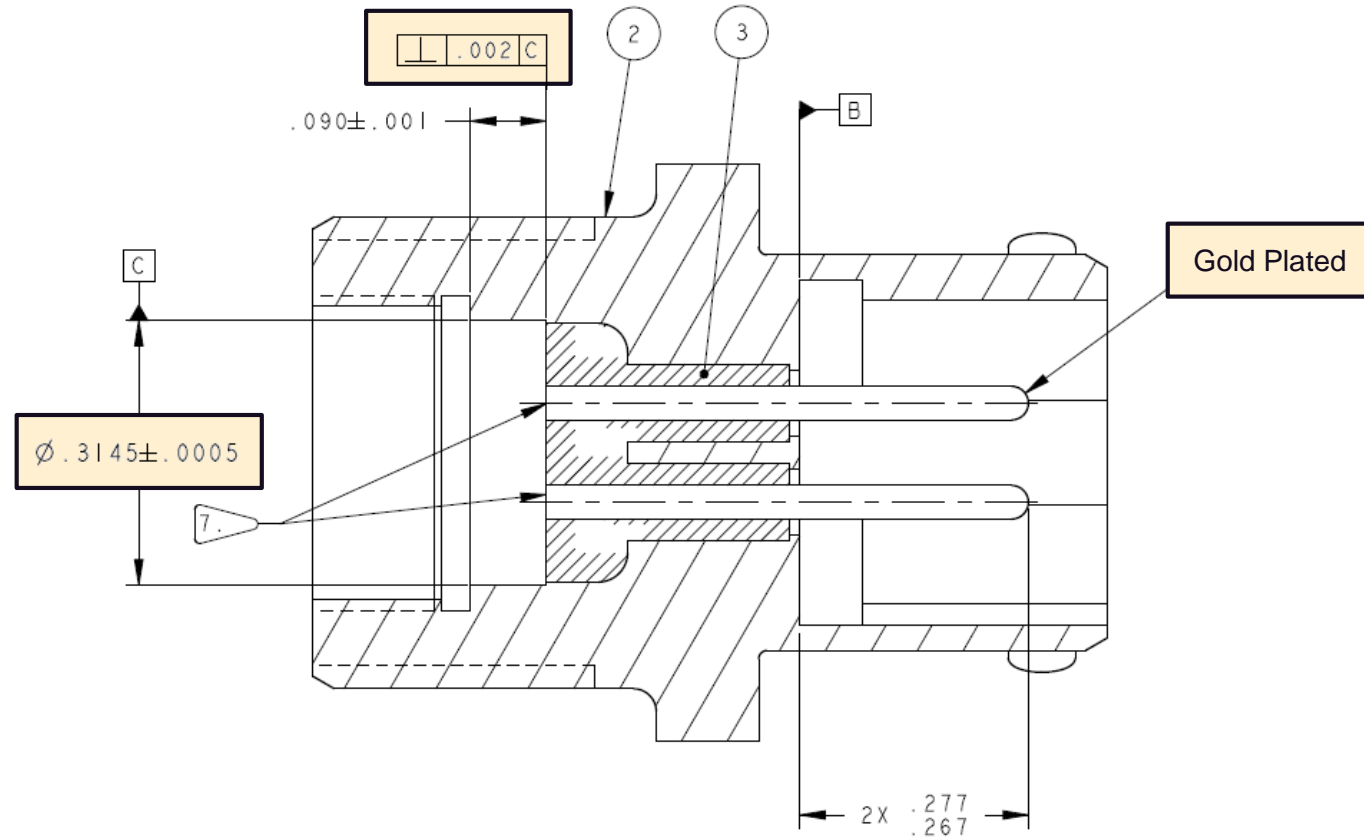
Process: centerless grinding

Header Shell (Inconel 718)



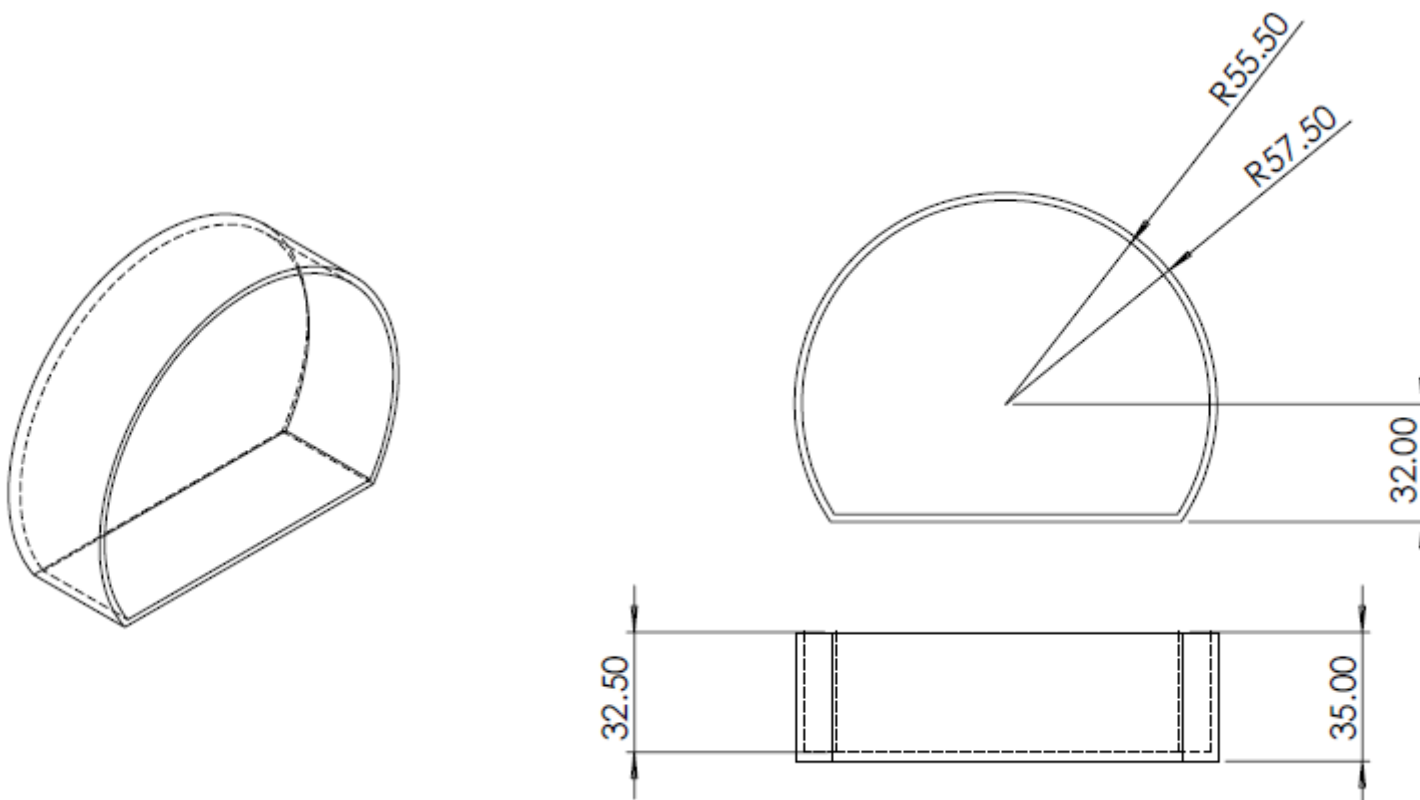
Processes: 5-axis machining, plunge EDM

Header Assembly (Inconel, Ceramic, Hastelloy)



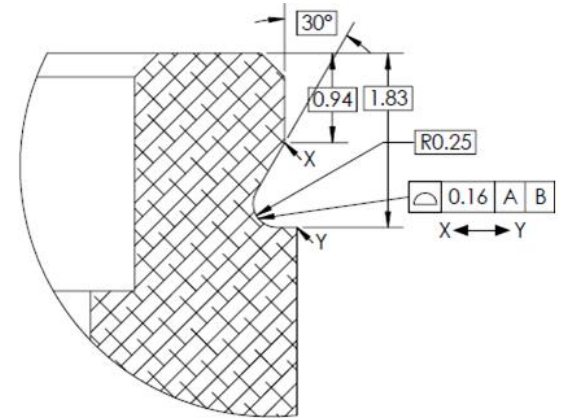
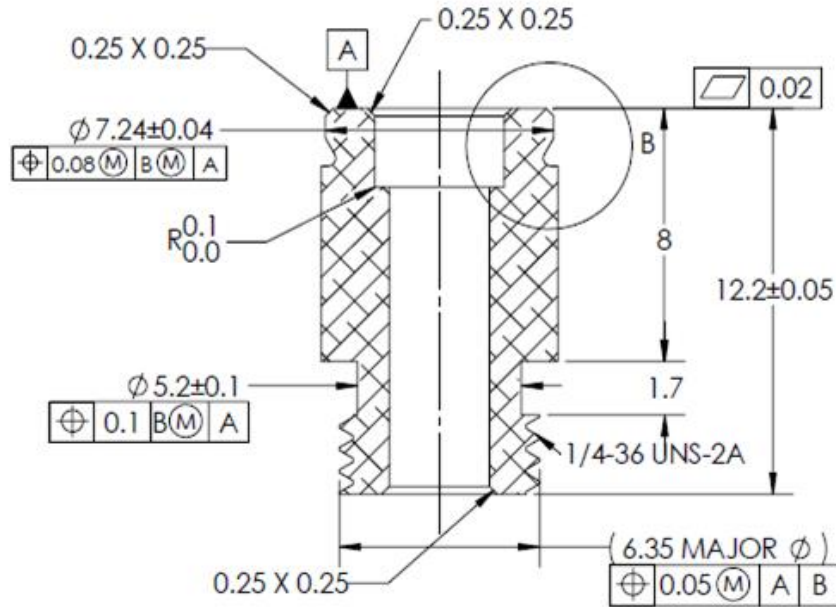
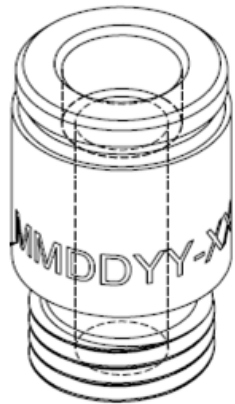
Process: high-speed plunge grinding or ultrasonic machining

Housing (Aluminum or Titanium)



Tolerances: <0.1 mm

Header (Aluminum)



Process: CNC machining

Firing Set (PCB Assembly)

Category	Quantity	Description
PCB	2	2 Layer through hole PCB ~2" x 2"
	2	2 Layer SMT PCB ~2" x 1"
	1	2 Layer SMT PCB ~4" x 1.5"
Components	8	e-Cap tantalum ~2000 μ F
	1	Ceramic Cap ~1 μ F
	13	Small SMT Resistors ~3mm x 2mm
	3	Large SMT Resistors 600K
	1	Transformer large Block/Square style
	1	Transformer IC Ring Style
	1	20 Pin Input/Output connector
	1	2 Pin Input/Output
	1	4 Pin Input/Output
	1	PCP to PCB connector (90 deg join style)
	3	Power MOSFET
	1	IC Op Amp
	2	Diode high power rated
	1	Opto-Isolator
	1	MOSFET Driver



Special requirements: radiation-hardened components